TAPING SPECIFICATION

1. APPLICATION

This document is applicable to FA-128

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[1] Taping specification

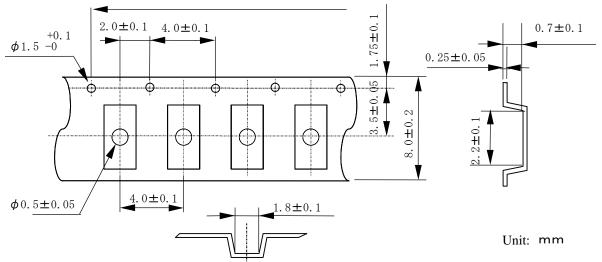
Subject to EIA-481 & IEC-60286

(1) Tape dimensions TE0804L

Material of the Carrier Tape: PS

Material of the Top Tape : PET+PE

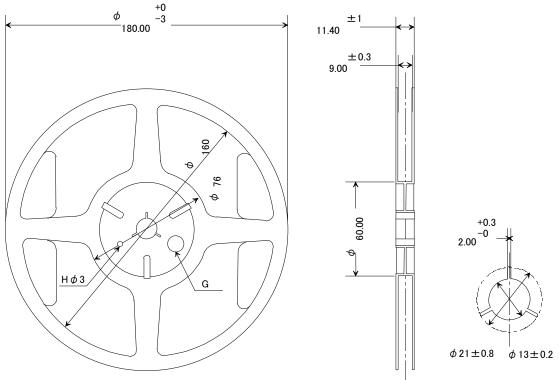
 $10P: 40\pm 0.15$



(2) Reel dimensions

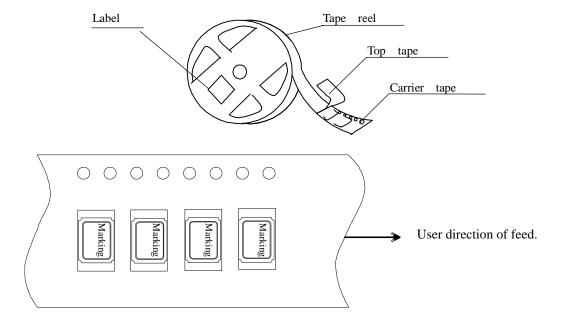
(a) Center material : PS

(b) Material of the Reel : PS

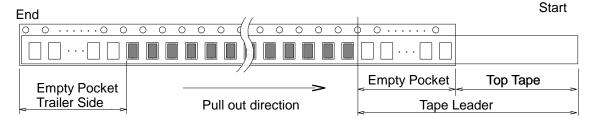


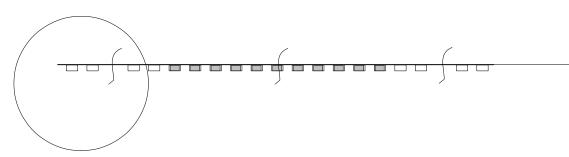
(3) Packing

(a) Tape & Reel



(b) Start & End Point





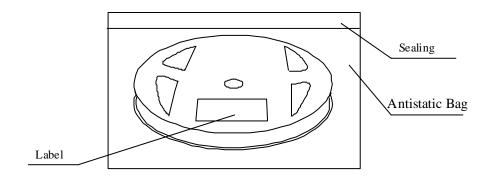
It	Empty Space			
Tape Leader	Top Tape	Min. 1 000 mm		
	Carrier Tape	Min. 100 mm		
Tape Trailer	Top Tape	Min. 0 mm		
	Carrier Tape	Min. 160 mm		

(4) Peel force of the cover tape

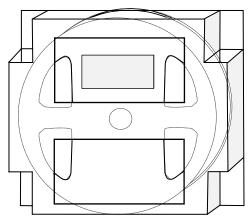
- \bigcirc angle : cover tape during peel off and the direction of unreeling shall be 165° to 180°.
- ② peel speed: 300 mm / min.
- 3 strength : 0.1 to 1 N.

[2] Inner Sleeve

a) Packing to antistatic bag

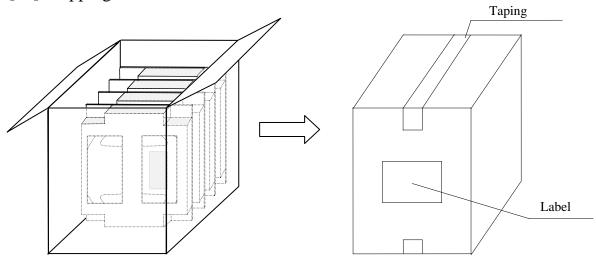


b) Packing to inner sleeve



* There is also a case to put the two reel.

[3] Shipping Carton



[4] Marking

- (1) Reel marking
 - Reel marking shall consist of:
 - 1) Parts name
 - 2) Quantity
 - 3) Manufacturing Date or symbol
 - 4) Manufacturer's Date or symbol
 - 5) Others (if necessary)
- (2) Shipping carton marking
 - Shipping carton marking shall consist of :
 - 1) Parts name
 - 2) Quantity

[5] Quantity

• 3 000 pcs./reel

[6] Storage environment

- (1) Before open the packing, we recommend to keep less than +30 °C and 85 %RH of Humidity, and to use it less than 6 months after delivery.
- (2) We recommend to open Package in immediately before use. After open Package, We recommend to keeps less than 6 month. No need dry air before soldering work if it is less than temperature +30 °C, 85 humidity %RH.
- (3) Not to expose the sun.
- (4) Not to storage with some erosive chemicals.
- (5) Nothing is allowed to put on the reel or carton to prevent mechanical damage.

[7] Handling

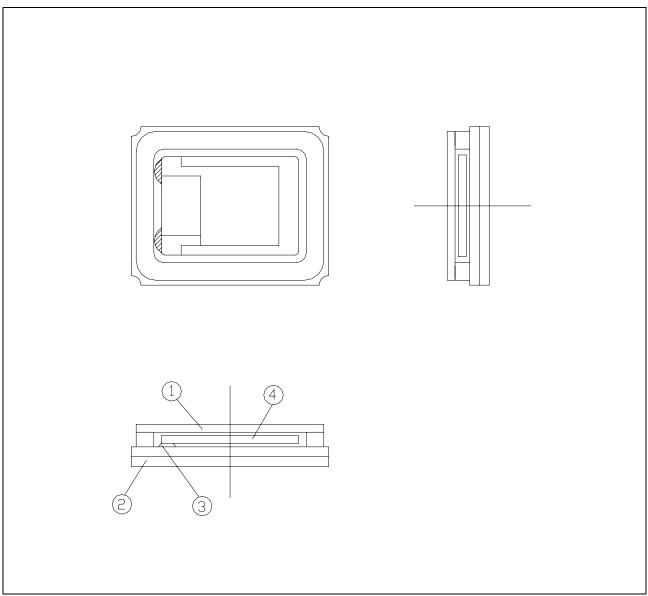
To handle with care to prevent the damage of tape, reel and products.

SMD TYPE AT STRIP CRYSTAL: FA-128

FA128_Q_0001 12.09.26

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			No.	Section	Standard	Inspection, Control items	Inspection method	Instrument	Record
(Crystal b	olock	1	Inspecting section.	Purchasing specification	Size.	Sampling.	Measure.	In-coming inspection
	∇				Incoming inspection standard	Outer appearance.	"	Visual inspection.	data sheet.
	\rightarrow					Inner appearance.	"	Visual inspection.	
		In-coming inspection	1'	Inspecting section.	"	Size.	Sampling.	Comparator.	<i>II</i>
	J					Outer appearance.	"	Micro scope.	
	2	Wafer cutting	2	Inspecting section.	Manufacturing instruction sheet	Cut angle.	Sampling.	X-ray raido grafic.	Process data sheet.
	J					Wafer thickness.	"	Comparator.	
Ceramic base	3	Wafer lapping	3	Producing section.	"	Frequency.	Sampling.	Frequency counter.	<i>II</i>
1 In-coming						Wafer thickness.	"	Comparator.	
inspection	4	Photo process	4	Producing section.	"	Size.	Sampling.	Comparator.	<i>''</i>
						Frequency.	"	Frequency counter.	
<u> </u>						Outer appearance.	//	Micro scope.	
Lid ▽	(5) 	Mounting	5	Producing section.	"	Outer appearance.	All insprcion.	Micro scope.	11
In-coming	6	Frequency adjustment	6	Producing section.	"	Frequency.	Sampling.	Network analyzer.	"
<u> </u>	7)	Welding	7	Producing section.	II .	Outer appearance.	Sampling.	Micro scope.	"
		, and the second	8	Producing section.	"	Airtightness check.	All insprcion.	Leak tester.	"
		Leak test		B. I			0 "	1 A .:	
	9	Marking	9	Producing section.	II	Outer appearance.	Sampling.	Micro scope.	"
			10	Producing section.	"	Crystal impedance.	All insprcion.	Inspectional machine.	<i>II</i>
	$\overline{\mathbb{Q}}$	Characteristic inspection				Frequency.	"	"	
						Insulation resistance.	"	"	
						Temp. characteristic.	Sampling.	"	
	(1)	Out-going inspection	11	Inspecting section.	Out-going inspection standard	Crystal impedance.	Sampling.	Inspection M/C.	Out-going inspection
	\top					Frequency.	"	"	data sheet.
						Insulation resistance.	"	"	
						Outer appearance.	"	Micro scope.	
	12	Taping	12	Producing section.	Manufacturing instruction sheet	Tape-peel strength.	Sampling.	Peelinf force tester.	Process data sheet.
	13	Packing	13	Product control section.	Manufacturing instruction sheet	Address.			Delivery slip.
					Packing instruction sheet	Quantity.	_	_	

Structure Diagram 構造図				
Model 型式	FA-128			
Document No. 管理No.	A-0502-A-1	FA-128_D_0001		



4	Crystal chip 水晶片
3	Crystal Adhesive 水晶接着
2	Package パッケージ
1	Lid リット*
No.	Name of Part 部品名

RELIABILITY TEST DATA

Product Name: FA-128

The Company evaluation condition

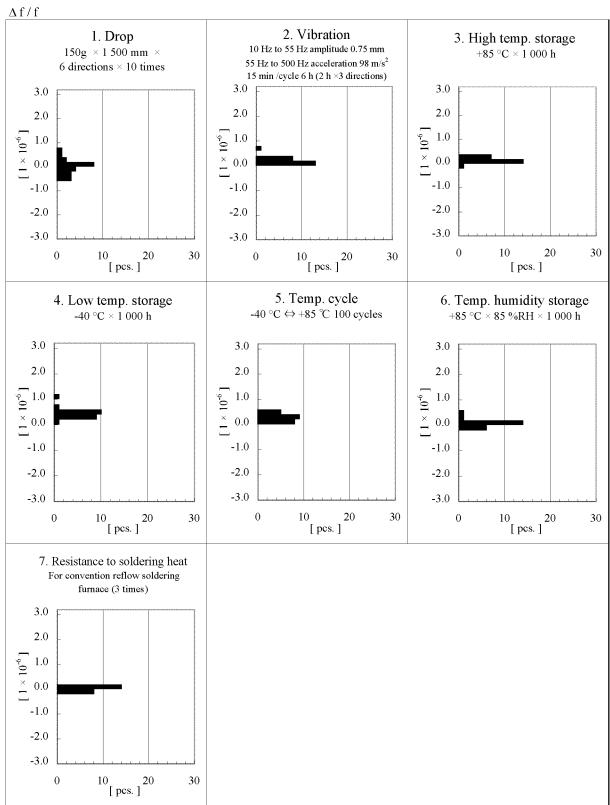
We evaluate environmental and mechanical characteristics by the following test condition.

		and meetament characteristics by the following	VALUE *1 *2	TEST	FAIL
No.	ITEM	TEST CONDITIONS	$\Delta f/f$	Qty	Qty
			$[1 \times 10^{-6}]$	[n]	[n]
1	Drop	150 g dummy Jig (Epsontoyocom Standard) drop from 1 500 mm height on the Concrete 6 directions 10 times	± 2	22	0
2	Vibration	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s ² 10 Hz \rightarrow 500 Hz \rightarrow 10 Hz 15 min / cycle 6 h (2 h × 3 directions)	*3 ± 2	22	0
3	High temperature storage	+85 °C × 1 000 h	± 2	22	0
4	Low temperature storage	-40 °C × 1 000 h	*3 ± 2	22	0
5	Temperature cycle	-40 °C ⇔ +85 °C 30 min at each temp. 100 cycles	± 2	22	0
6	Temperature humidity storage	+85 °C × 85 %RH × 1 000 h	± 2	22	0
7	Resistance to soldering heat	For convention reflow soldering furnace (3 times)	± 2	22	0
8	Substrate bending	Bend width reaches 3.0 mm and hold for $5 \text{ s} \pm 1 \text{ s} \times 1 \text{ time}$ Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
9	Shear	10 N press for 10 s ± 1 s Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
10	Pull - off	10 N press for 10 s ± 1 s Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
11	Solderability	Dip termination into solder bath at +235°C ± 10 °C for 5 s (Using Rosin Flux)	Termination must be 95 % covered with fresh solder	11	0

Notes

- 1. *1 Each test done independently.
- 2. *2 Measuring 2 h to 24 h later leaving in room temperature after each test.
- 3. *3 Measuring 24 h later leaving in room temperature after each test.
 - 1. Reflow 3 times
 - 2. Initial value shall be after 24h at room temperature.
- 4. Shift series resistance at before above tests should be less than ± 20 % or less than ± 10 Ω .

Product Name: FA-128



Product Name: FA-128

